



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20230508000.1A

**Qualification of RFAB as an additional Fab site option for select LBC7 devices
Change Notification / Sample Request**

Date: July 17, 2023

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

PCN Revision A is to announce the retraction of select devices.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services



20230508000.1A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV1117LV33DCYT	null
LP5912-1.0DRV1T	null
LP5912-2.8DRV1T	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20230508000.1A		PCN Date:	July 17, 2023																			
Title:	Qualification of RFAB as an additional Fab site option for select LBC7 devices																						
Customer Contact:	Change Management team		Dept:	Quality Services																			
Proposed 1st Ship Date:	Aug 8, 2023		Sample requests accepted until:	Jun 8, 2023*																			
*Sample requests received after June 8, 2023 will not be supported.																							
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
<p>The purpose of PCN Revision A is to announce the retraction of select devices. Retracted devices are identified with a strikethrough and are highlighted in yellow in the Product Affected Section. Retracted devices are no longer impacted by this PCN.</p> <p>Texas Instruments is pleased to announce the qualification of an additional fab (RFAB) site for selected devices as listed below in the product affected section.</p>																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>MIHO</td> <td>LBC7</td> <td>200 mm</td> <td>RFAB</td> <td>LBC7</td> <td>300 mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	MIHO	LBC7	200 mm	RFAB	LBC7	300 mm
Current Fab Site			Additional Fab Site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																		
MIHO	LBC7	200 mm	RFAB	LBC7	300 mm																		
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Continuity of Supply																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Changes to product identification resulting from this PCN:																							
Fab Site Information:																							
Chip Site		Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																			
MIHO8		MH8	JPN	Ibaraki																			
RFAB		RFB	USA	Richardson																			
Sample product shipping label (not actual product label)																							
<div style="display: flex; justify-content: space-between; align-items: flex-start;"> <div style="width: 30%;">  <p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:</p> <table border="1"> <tr> <td>MSL 2 / 260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p> </div> <div style="width: 20%; text-align: center;">  </div> <div style="width: 40%;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS</p> </div> </div>						MSL 2 / 260C/1 YEAR	SEAL DT	MSL 1 / 235C/UNLIM	03/29/04														
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MSL 1 / 235C/UNLIM	03/29/04																						

Product Affected:

LP5912-0.9DRV R	SN1708041DDCR	TPS54228DRCR	TPS62112RSAT
LP5912-0.9DRV T	SN1708041DDCT	TPS54228DRCT	TPS62160DGKR
LP5912-1.0DRV R	SN1711021DDCR	TPS54308DDCR	TPS62160DGKT
LP5912-1.0DRV T	SN1711021DDCT	TPS54308DDCT	TPS62170DSGR
LP5912-1.1DRV R	TLV1117LV33DCYR	TPS560200DBVR	TPS62170DSGT
LP5912-1.1DRV T	TLV1117LV33DCYT	TPS560200DBVT	UCC27511ADBVR
LP5912-1.2DRV R	TLV70310DBVR	TPS562210ADDFR	UCC27511ADBVT
LP5912-1.2DRV T	TLV70311DBVR	TPS562210ADDFT	UCC27531D
LP5912-1.5DRV R	TLV70312DBVR	TPS562210DDFR	UCC27531DBVR
LP5912-1.5DRV T	TLV70313DBVR	TPS562210DDFT	UCC27531DBVT
LP5912-1.8DRV R	TLV70315DBVR	TPS562219ADDFR	UCC27531DR
LP5912-1.8DRV T	TLV70318DBVR	TPS562219ADDFT	UCC27532DBVR
LP5912-2.5DRV R	TLV70325DBVR	TPS562219DDFR	UCC27532DBVT
LP5912-2.5DRV T	TLV70327DBVR	TPS562219DDFT	UCC27533DBVR
LP5912-2.8DRV R	TLV70328DBVR	TPS62110RSAR	UCC27533DBVT
LP5912-2.8DRV T	TLV70329DBVR	TPS62110RSARG4	UCC27536DBVR
LP5912-3.0DRV R	TLV70330DBVR	TPS62110RSAT	UCC27536DBVT
LP5912-3.0DRV T	TLV70333DBVR	TPS62110RSAT G4	UCC27537DBVR
LP5912-5.0DRV R	TPS27081ADDCR	TPS62111RSAR	UCC27537DBVT
LP5912-5.0DRV T	TPS54227DRCR	TPS62111RSARG4	UCC27538DBVR
SN0603044RSAR	TPS54227DRCT	TPS62111RSAT	UCC27538DBVT
SN1706011DDCR	TPS54228D	TPS62112RSAR	
SN1706011DDCT	TPS54228DR	TPS62112RSARG4	

Qualification Report**Approve Date 6-October-2010****Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS51217DSC
ED	Electrical Characterization	Per Datasheet Parameters	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
AC	Autoclave, 121C	96 Hours	3/231/0
HBM	ESD - HBM	2000 V	3/9/0
CDM	ESD - CDM	500 V	3/9/0
HTOL	Life Test, 135C	635 Hours	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0
LU	Latch-up	(per JESD78)	3/18/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/18/0

- Qual Device TPS51217DSC is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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